

MSM514256RS/JS/ZS**262,144-WORD × 4-BITS DYNAMIC RAM****GENERAL DESCRIPTION**

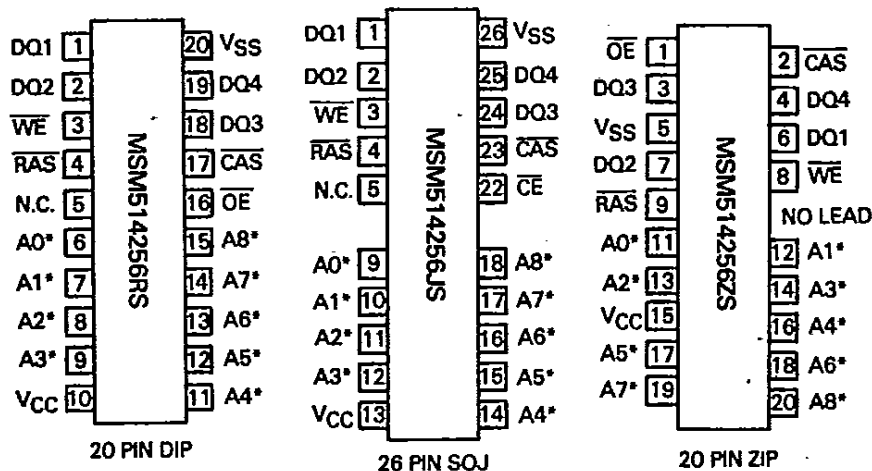
The MSM514256 is a new generation dynamic RAM organized as 262,144 words by 4 bits. The technology used to fabricate the MSM514256 is OKI's CMOS silicon gate process technology. The device operates at a single +5V power supply. Its I/O pins are TTL compatible.

FEATURES

- Silicon gate, tripple polysilicon CMOS, 1-transistor memory cell
- 262,144 words by 4 bits
- Standard 20-pin plastic DIP
- Family organization

Family	Access Time (MAX)	Cycle Time (MIN)	Power Dissipation	
			Operating (MAX)	Standby (MAX)
MSM514256-10	100 ns	190 ns	413 mW	5.5 mW
MSM514256-12	120 ns	220 ns	385 mW	

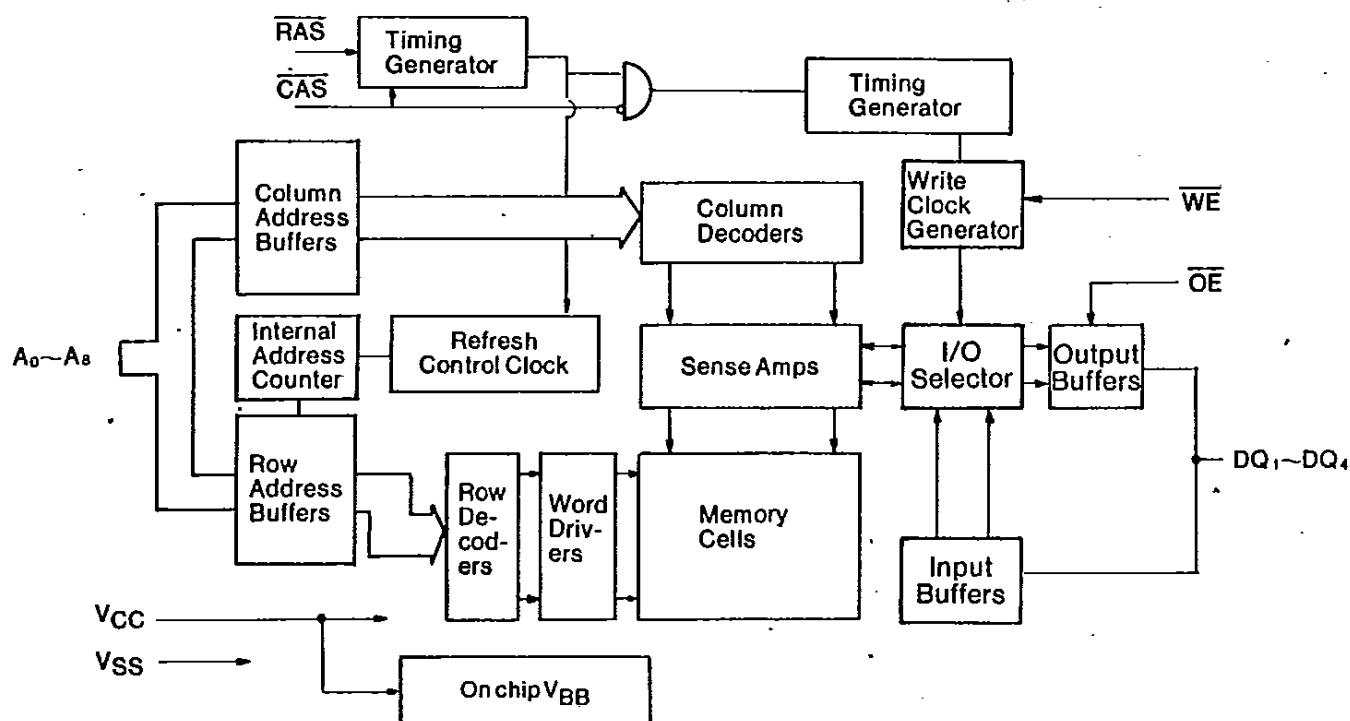
- Single +5V supply, $\pm 10\%$ tolerance
- Input: TTL compatible, address input, data input latch
- Output: TTL compatible, tristate, nonlatch
- Refresh: 512 cycles/8 ms
- Output impedance controllable through early write and OE operations
- Fast page mode, read/write capability
- CAS before RAS refresh, CAS before RAS hidden refresh, RAS only refresh capability
- "Gated" CAS
- Built-in V_{BB} generator circuit

PIN CONFIGURATION (TOP VIEW)

Pin Names	Function
A0 to A8	Address Input
$\overline{\text{RAS}}$	Row Address Strobe
$\overline{\text{CAS}}$	Column Address Strobe
DQ1 to DQ4	Data In/Data Out
$\overline{\text{OE}}$	Output Enable
$\overline{\text{WE}}$	Write Enable
VCC	Power Supply (+5V)
VSS	Ground (0V)
N.C.	No Connection

* Refresh Address

FUNCTIONAL BLOCK DIAGRAM



ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Conditions	Value	Unit
Voltage on any pin relative to V_{SS}	V_T	$T_a = 25^\circ\text{C}$	-1.0 to +7.0	V
Short circuit output current	I_{OS}	$T_a = 25^\circ\text{C}$	50	mA
Power dissipation	P_D	$T_a = 25^\circ\text{C}$	1	W
Operating temperature	T_{opr}	—	0 to +70	$^\circ\text{C}$
Storage temperature	T_{stg}	—	-55 to +150	$^\circ\text{C}$

RECOMMENDED OPERATING CONDITIONS

($T_a = 0$ to $+70^\circ$)

Parameter	Symbol	Conditions	MIN	TYP	MAX	Unit
Supply Voltage	V_{CC}	—	4.5	5.0	5.5	V
	V_{SS}	—	0	0	0	V
Input high voltage	V_{IH}	—	2.4	—	6.5	V
Input low voltage	V_{IL}	—	-1.0	—	0.8	V

DC CHARACTERISTICS

($V_{CC} = 5V \pm 10\%$, $T_a = 0$ to $+70^{\circ}C$)

Parameter	Symbol	Conditions	MSM 514256-10		MSM 514256-12		Unit	Note
			MIN	MAX	MIN	MAX		
Output high voltage	V_{OH}	$I_{OH} = -5.0\text{ mA}$	2.4	V_{CC}	2.4	V_{CC}	V	
Output low voltage	V_{OL}	$I_{OL} = 4.2\text{ mA}$	0	0.4	0	0.4	V	
Input leakage current	I_{LI}	$0V \leq V_I \leq 6.5V$; all other pins not under test = 0V	-10	10	-10	10	μA	
Output leakage current	I_{LO}	DOUT disable $0V \leq V_O \leq 5.5V$	-10	10	-10	10	μA	
Average power supply current* (Operating)	I_{CC1}	$\overline{RAS}$, $\overline{CAS}$ cycling, $t_{RC} = \min$	-	75	-	70	mA	
Power supply current* (Standby)	I_{CC2}	$\overline{RAS} = V_{IH}$ $\overline{CAS} = V_{IH}$ DOUT = HZ	TTL	-	2	-	2	mA
			MOS	-	1	-	1	
Average power supply current* (RAS only refresh)	I_{CC3}	$\overline{RAS}$ cycling, $\overline{CAS} = V_{IH}$ $t_{RC} = \min$	-	75	-	70	mA	
Average power supply current* (CAS before RAS refresh)	I_{CC6}	$\overline{RAS}$ cycling, $\overline{CAS}$ before $\overline{RAS}$	-	75	-	70	mA	
Average power supply current* (Fast page mode)	I_{CC7}	$\overline{RAS} = V_{IL}$, $\overline{CAS}$ cycling $t_{PC} = \min$	-	55	-	50	mA	

***Note:** I_{CC} is dependent on output loading and cycle rates. Specified values are obtained with the output open.

CAPACITANCE

($T_a = 25^{\circ}C$, $f = 1\text{ MHz}$)

Parameter	Symbol	Conditions	TYP	MAX	Unit
Input capacitance (A0 to A8)	C_{IN1}	-	-	6	pF
Input capacitance ($\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$)	C_{IN2}	-	-	7	pF
Output capacitance (DQ1 to DQ4)	$C_{I/O}$	-	-	7	pF

Parameter	Symbol	MSM514256-10		MSM514256-12		Unit	Note
		MIN	MAX	MIN	MAX		
Refresh period	t _{REF}	—	8	—	8	ms	
Random read or write cycle time	t _{RC}	190	—	220	—	ns	
Read/write cycle time	t _{RWC}	255	—	295	—	ns	
Fast page mode cycle time	t _{PC}	55	—	70	—	ns	
Fast page mode read/write cycle time	t _{PRMW}	120	—	140	—	ns	
Access time from $\overline{\text{RAS}}$	t _{RAC}	—	100	—	120	ns	4, 5, 6
Access time from $\overline{\text{CAS}}$	t _{CAC}	—	35	—	45	ns	4, 5
Access time from column address	t _{AA}		50		60	ns	4, 6
Access time from $\overline{\text{CAS}}$ precharge	t _{CPA}	—	50	—	65	ns	4
Output low impedance time from $\overline{\text{CAS}}$	t _{CLZ}	0	—	0	—	ns	4
Output buffer turn-off delay	t _{OFF}	0	25	0	30	ns	
Transition time	t _T	3	50	3	50	ns	3
$\overline{\text{RAS}}$ precharge time	t _{RP}	80	—	90	—	ns	
$\overline{\text{RAS}}$ pulse width	t _{RAS}	100	10000	120	10000	ns	
$\overline{\text{RAS}}$ hold time	t _{RSH}	35	—	45	—	ns	
$\overline{\text{CAS}}$ precharge time (Fast page mode cycle only)	t _{CP}	10	—	15	—	ns	
$\overline{\text{CAS}}$ pulse width	t _{CAS}	35	10000	45	10000	ns	
$\overline{\text{CAS}}$ hold time	t _{CSH}	100	—	120	—	ns	
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ delay time	t _{RCD}	25	65	25	75	ns	5
$\overline{\text{RAS}}$ to column address delay time	t _{RAD}	20	50	20	60	ns	6
$\overline{\text{CAS}}$ to $\overline{\text{RAS}}$ precharge time	t _{CRP}	10	—	10	—	ns	
Row address set-up time	t _{ASR}	0	—	0	—	ns	
Row address hold time	t _{RAH}	15	—	15	—	ns	
Column address set-up time	t _{ASC}	0	—	0	—	ns	
Column address hold time	t _{CAH}	20	—	25	—	ns	
Column address hold time from $\overline{\text{RAS}}$	t _{AR}	75	—	90	—	ns	
Column address to $\overline{\text{RAS}}$ lead time	t _{RAL}	50	—	60	—	ns	

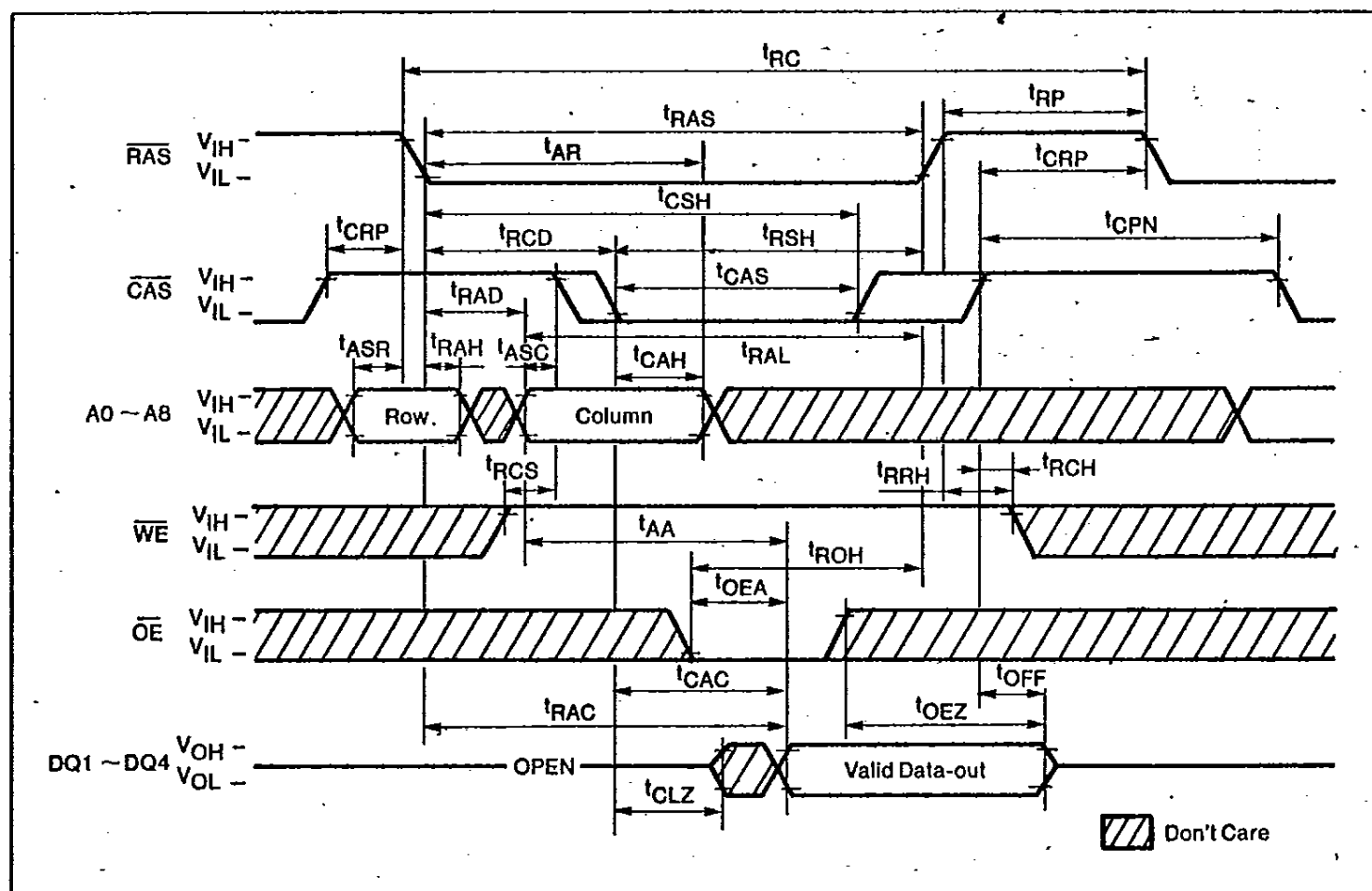
AC CHARACTERISTICS (CONT.)

Parameter	Symbol	MSM514256-10		MSM514256-12		Unit	Note
		MIN	MAX	MIN	MAX		
Read command set-up time	t_{RCS}	0	—	0	—	ns	
Read command hold time	t_{RCH}	0	—	0	—	ns	8
Write command hold time from $\overline{RAS}$	t_{WCR}	75	—	90	—	ns	
Write command set-up time	t_{WCS}	0	—	0	—	ns	7
Write command hold time	t_{WCH}	20	—	25	—	ns	
Write command pulse width	t_{WP}	20	—	25	—	ns	
Write command to $\overline{RAS}$ lead time	t_{RWL}	25	—	30	—	ns	
Write command to $\overline{CAS}$ lead time	t_{CWL}	25	—	30	—	ns	
Data-in set-up time	t_{DS}	0	—	0	—	ns	
Data-in hold time	t_{DH}	20	—	25	—	ns	
Data-in hold time from $\overline{RAS}$	t_{DHR}	75	—	90	—	ns	
$\overline{CAS}$ to $\overline{WE}$ delay	t_{CWD}	70	—	85	—	ns	7
$\overline{RAS}$ to $\overline{WE}$ delay	t_{RWD}	135	—	160	—	ns	7
Column address to $\overline{WE}$ delay time	t_{AWD}	85	—	100	—	ns	7
Read command hold time reference to $\overline{RAS}$	t_{RRH}	10	—	10	—	ns	8
$\overline{RAS}$ to $\overline{CAS}$ set-up time (CAS before $\overline{RAS}$)	t_{CSR}	10	—	10	—	ns	
$\overline{RAS}$ to $\overline{CAS}$ hold time (CAS before $\overline{RAS}$)	t_{CHR}	30	—	30	—	ns	
$\overline{CAS}$ active delay from $\overline{RAS}$ precharge	t_{RPC}	10	—	10	—	ns	
$\overline{CAS}$ precharge time (Refresh counter test)	t_{CPT}	50	—	60	—	ns	
$\overline{CAS}$ precharge time	t_{CPN}	15	—	20	—	ns	
$\overline{RAS}$ hold time reference to $\overline{OE}$	t_{ROH}	20	—	20	—	ns	
Access time from $\overline{OE}$	t_{OEA}	—	25	—	30	ns	
$\overline{OE}$ delay time	t_{OED}	25	—	30	—	ns	
$\overline{OE}$ to data output buffer turn-off delay	t_{OEZ}	0	25	0	30	ns	
$\overline{OE}$ command hold time	t_{OEH}	25	—	30	—	ns	

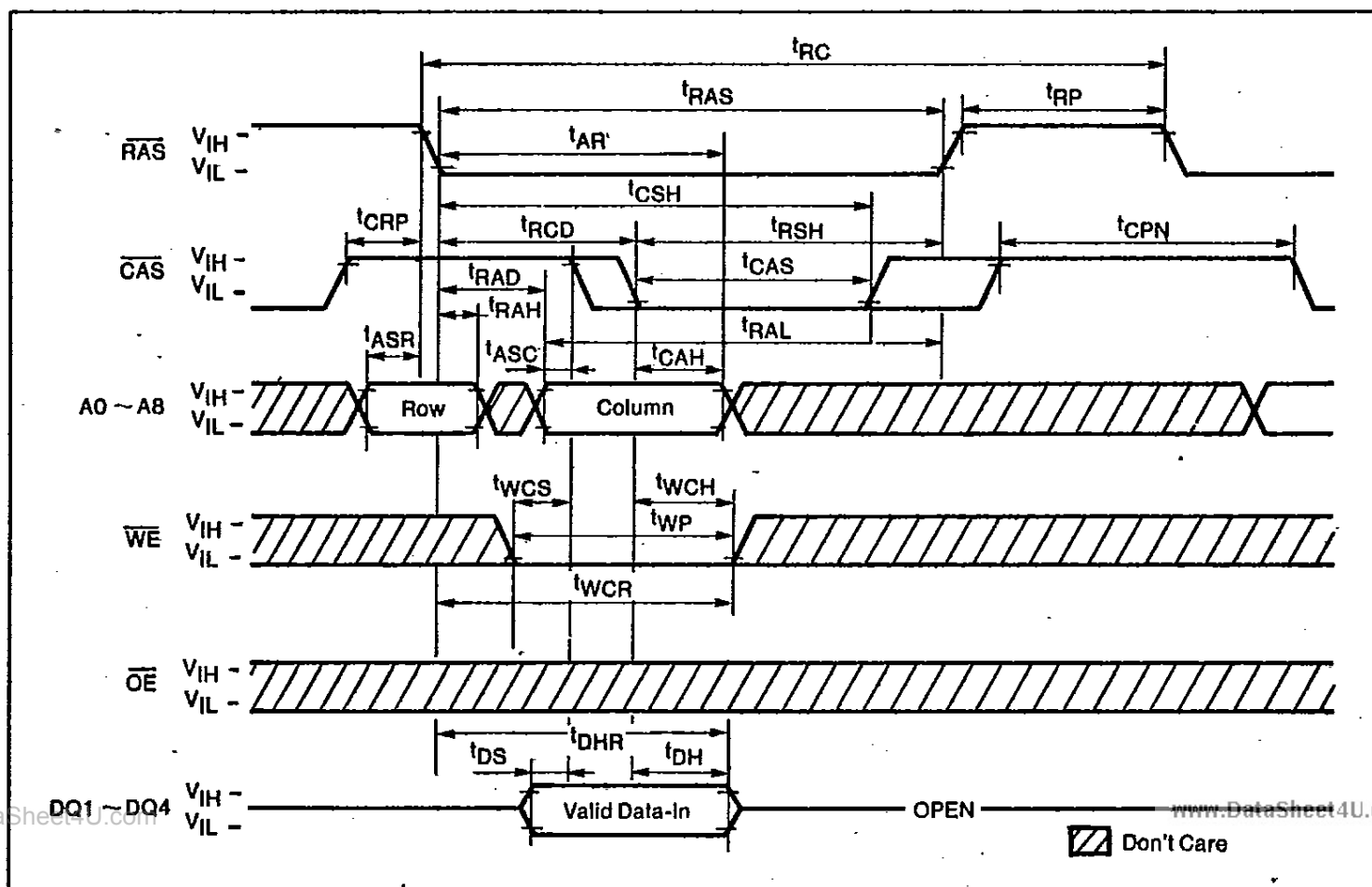
- Notes:**
- 1 An initial pause of 100 μ s is required after power-up followed by any 8 $\overline{\text{RAS}}$ cycles (Example: $\overline{\text{RAS}}$ only) before proper device operation is achieved.
 - 2 The AC characteristics assume at $t_T = 5$ ns.
 - 3 V_{IH} (min.) and V_{IL} (max.) are reference levels for measuring of input signals. Also, transition times are measured between V_{IH} and V_{IL} .
 - 4 Measured with a load circuit equivalent to 2TTL + 100 pF.
 - 5 Operation within the t_{RCD} (max.) limit insures that t_{RAC} (max.) can be met. t_{RCD} (max.) is specified as a reference point only; if t_{RCD} is greater than the specified t_{RCD} (max.) limit, then access time is controlled exclusively by t_{CAC} .
 - 6 Operation within the t_{RAD} (max.) limit insures that t_{RAC} (max.) can be met. t_{RAD} (max.) is specified as a reference point only; if t_{RAD} is greater than the specified t_{RAD} (max.) limit, then access time is controlled exclusively by t_{AA} .
 - 7 t_{WCS} , t_{CWD} , t_{RWD} and t_{AWD} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only; if $t_{WCS} \geq t_{WCS}(\text{min.})$ the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if $t_{CWD} \geq t_{CWD}(\text{min.})$, $t_{RWD} \geq t_{RWD}(\text{min.})$ and $t_{AWD} \geq t_{AWD}(\text{min.})$, the cycle is read/write cycle and the data out will contain data read from the selected cell; if neither of the above sets of conditions is satisfied the condition of the data out (at access time) is indeterminate.
 - 8 Either t_{RRH} or t_{RCH} must be satisfied for a read cycle.

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READ CYCLE

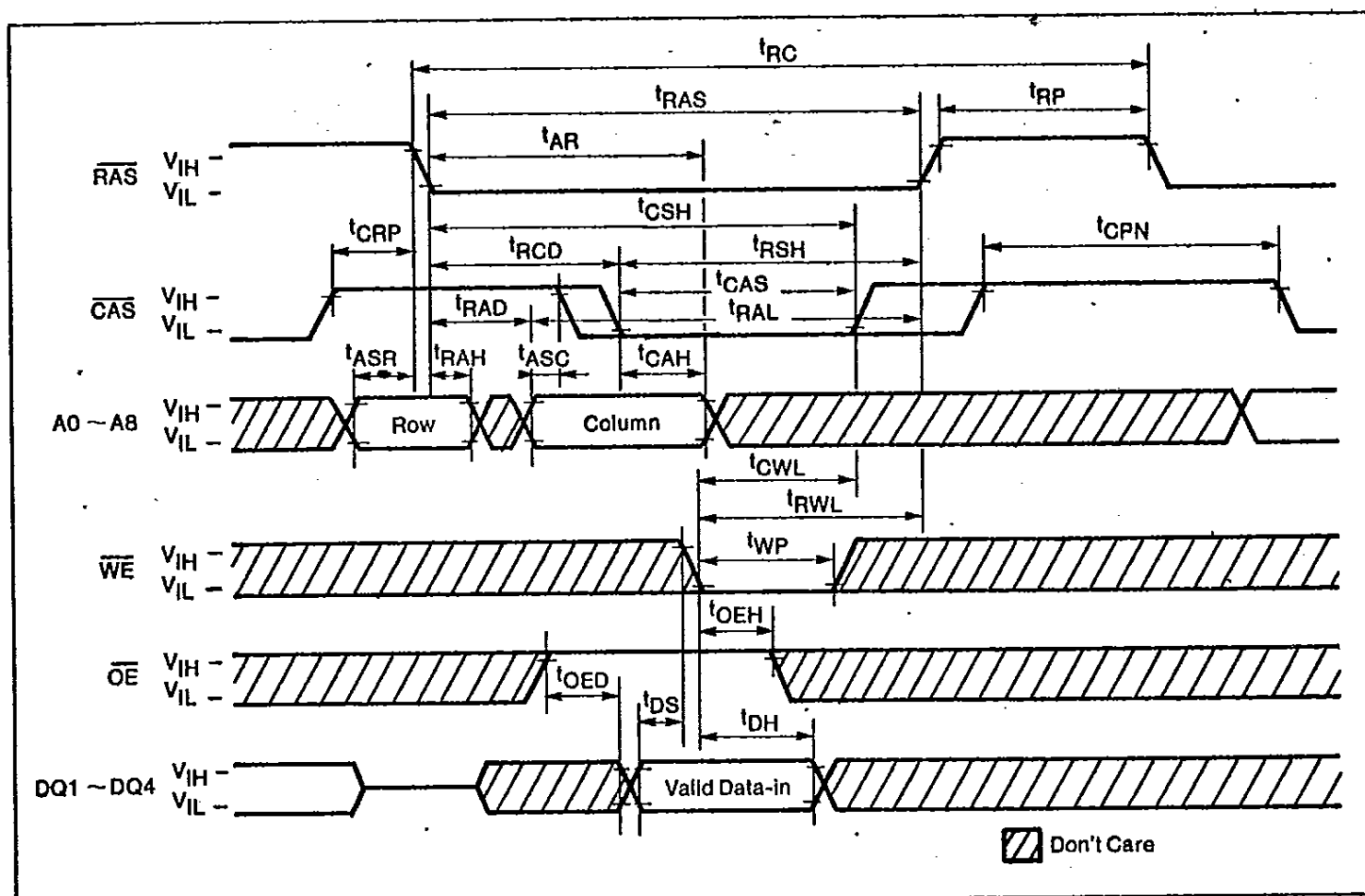


WRITE CYCLE (EARLY WRITE)

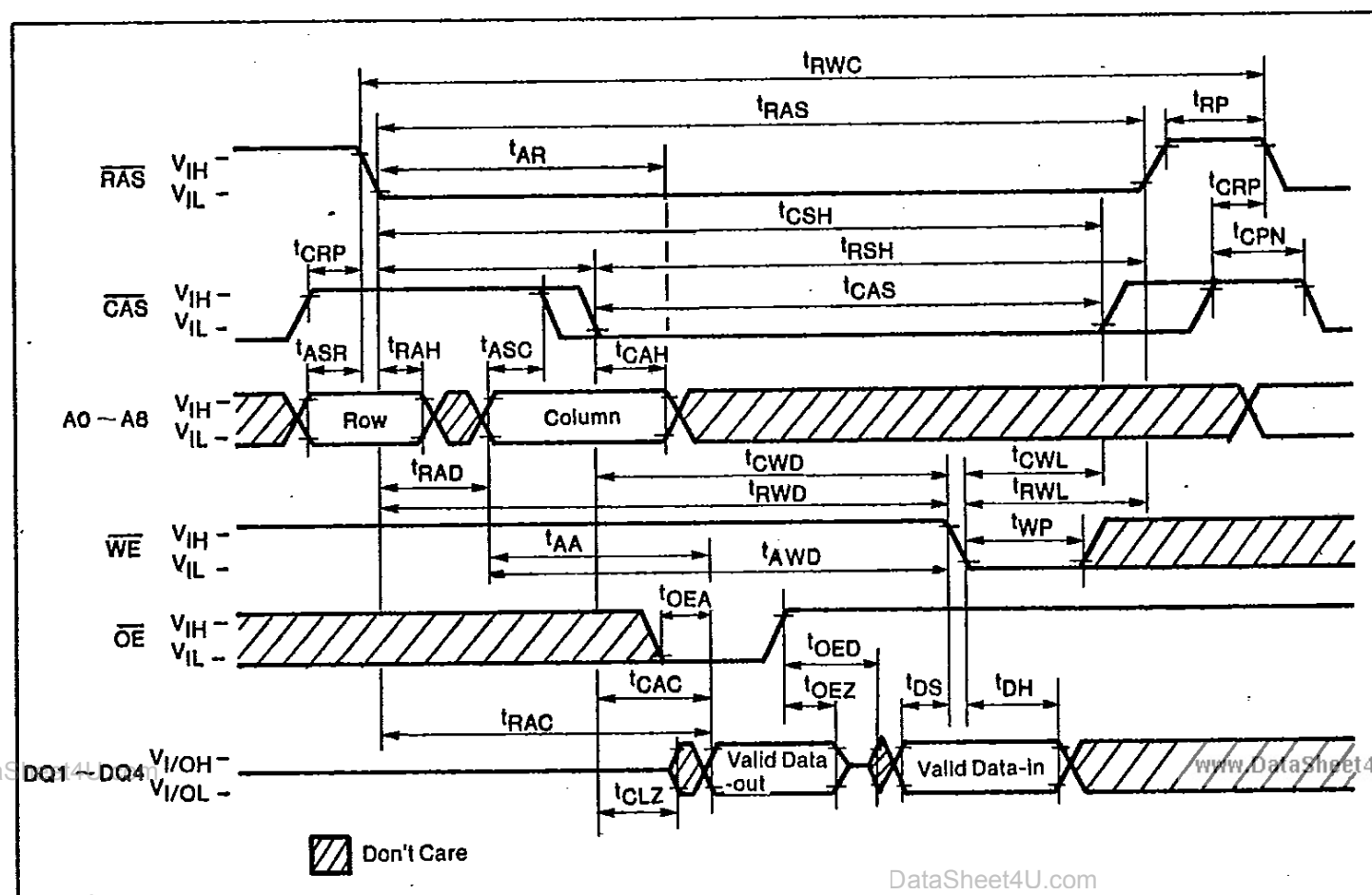


WRITE CYCLE ($\overline{\text{OE}}$ CONTROL WRITE)

T-46-23-17



READ/WRITE CYCLE





DataSheet

DataSheet



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The diagram illustrates the timing relationships for the 64K1602 LCD module. It shows the signals RAS, CAS, A0~A8, WE, OE, and DQ1~DQ4. The timing parameters are defined as follows:

- t_{RAS} : RAS pulse width
- t_{AR} : RAS access time
- t_{CSH} : CAS setup time
- t_{RCD} : RAS to CAS delay
- t_{CAS} : CAS pulse width
- t_{CP} : CAS to RAS delay
- t_{PRMW} : Precharge time
- t_{RSH} : RAS setup time
- t_{CRP} : CAS to RAS delay
- t_{RAD} : RAS access time
- t_{RAH} : RAS hold time
- t_{ASR} : Address setup time
- t_{ASC} : Address setup time
- t_{CAH} : Column address hold time
- t_{ASC} : Address setup time
- t_{CAH} : Column address hold time
- t_{RCS} : RAS to CAS delay
- t_{RWD} : RAS to WE delay
- t_{CWD} : Column address to WE delay
- t_{CWL} : Column address to WE delay
- t_{AWD} : Address to WE delay
- t_{WP} : WE pulse width
- t_{OEZ} : OEZ delay
- t_{AA} : Address to OEZ delay
- t_{CAC} : Column address to OEZ delay
- t_{RAC} : RAS to OEZ delay
- t_{DS} : Data setup time
- t_{DH} : Data hold time
- t_{CLZ} : CLZ delay
- t_{RWL} : RAS to WE delay
- t_{CWL} : Column address to WE delay
- t_{ROH} : RAS to OEZ delay
- t_{WP} : WE pulse width
- t_{OEZ} : OEZ delay
- t_{AA} : Address to OEZ delay
- t_{CAC} : Column address to OEZ delay
- t_{RAC} : RAS to OEZ delay
- t_{DS} : Data setup time
- t_{DH} : Data hold time
- t_{CLZ} : CLZ delay

The diagram also shows the data bus DQ1~DQ4 with signals OUT, IN, and CLZ. The signals are labeled as V_{IH} and V_{IL} for high and low levels, and V_{I/OH} and V_{I/OL} for output high and low levels. The signals are labeled as "Don't Care" for the OUT and IN signals.

Timing diagram for the 74VHC04 inverter. The diagram shows three signals: $\overline{\text{RAS}}$, $\overline{\text{CAS}}$, and $\text{A0} \sim \text{A8}$.

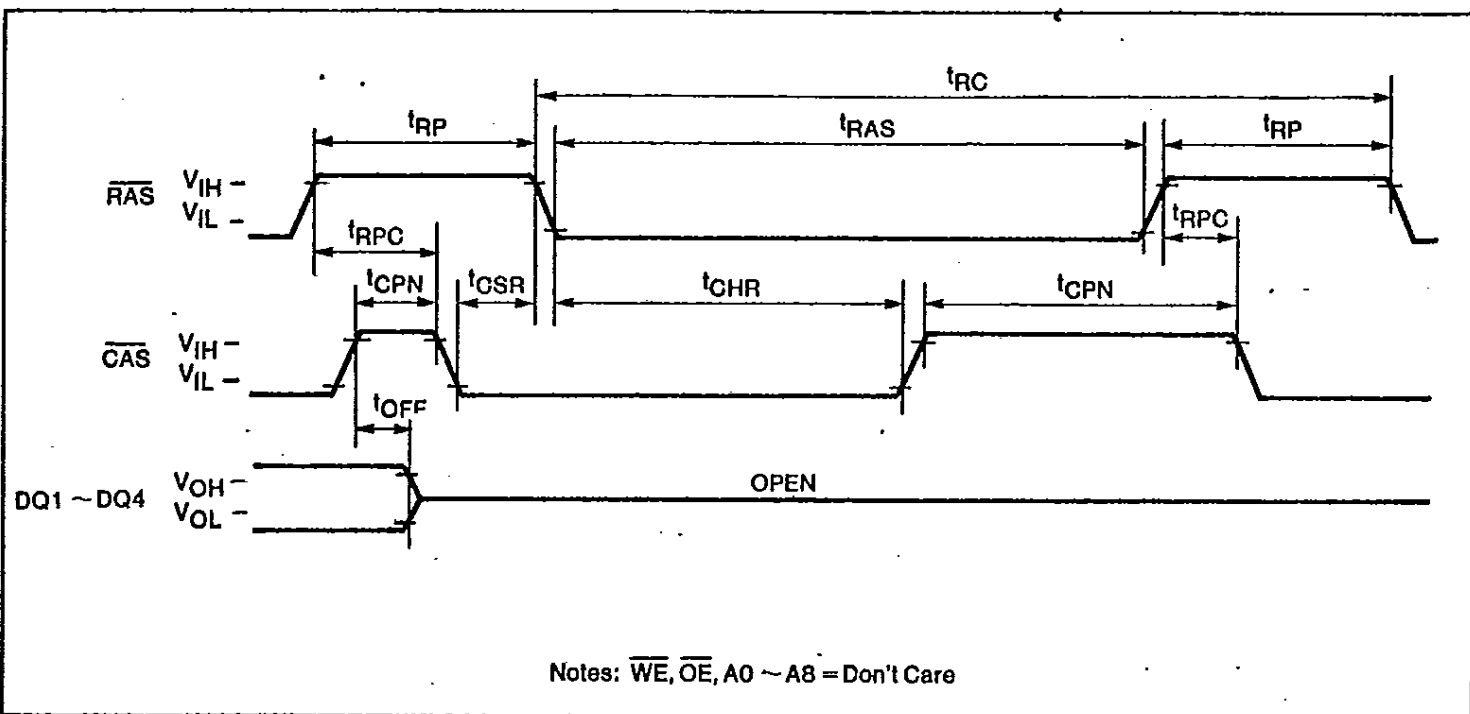
Parameters shown:

- t_{RAS} : Pulse width of $\overline{\text{RAS}}$.
- t_{CRP} : Setup time for $\overline{\text{RAS}}$ before $\overline{\text{CAS}}$ goes high.
- t_{RPC} : Hold time for $\overline{\text{RAS}}$ after $\overline{\text{CAS}}$ goes low.
- t_{RC} : Total cycle time of $\overline{\text{RAS}}$.
- t_{RP} : Pulse period of $\overline{\text{RAS}}$.
- t_{AS} : Setup time for $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ goes low.
- t_{RAH} : Hold time for $\overline{\text{CAS}}$ after $\overline{\text{RAS}}$ goes high.

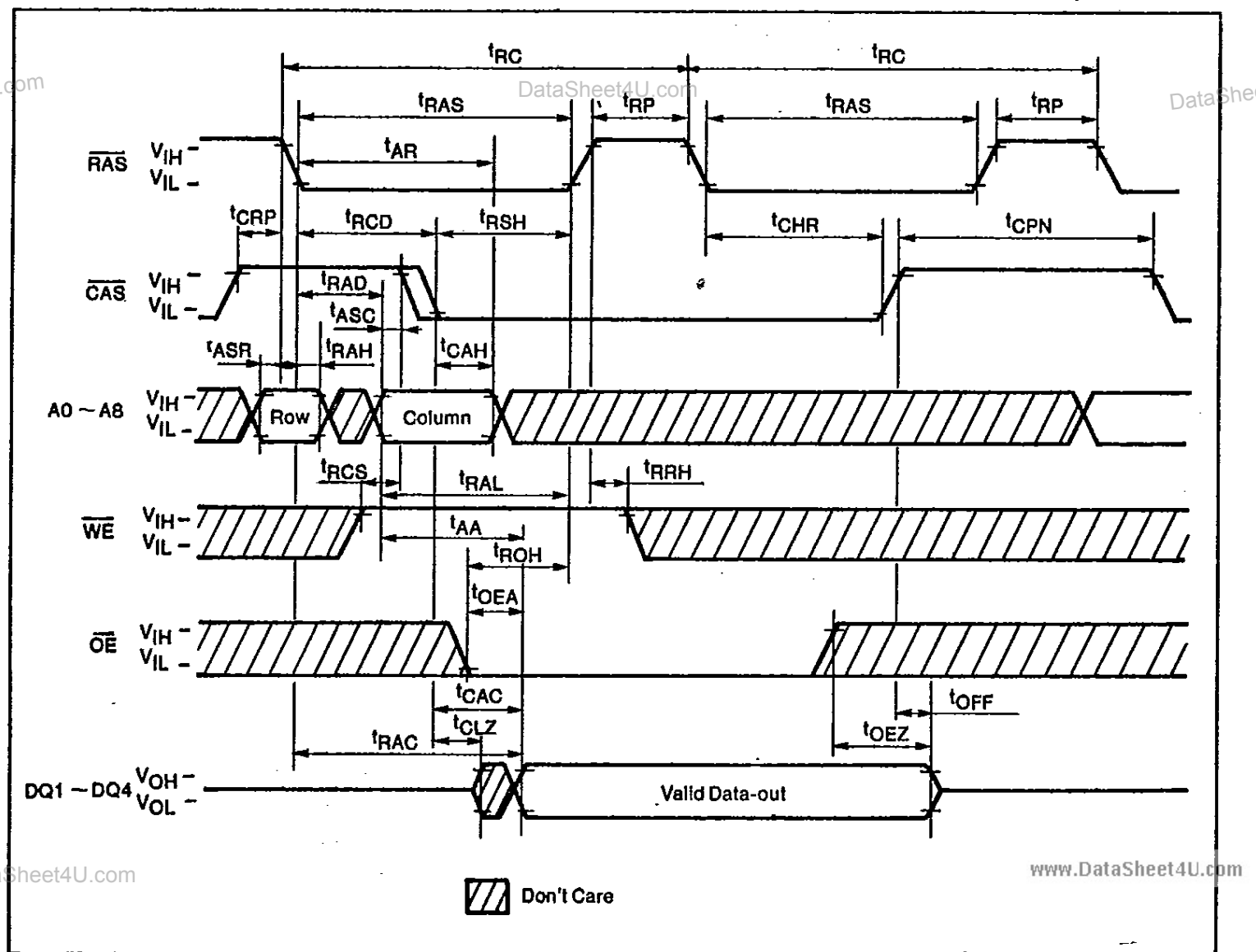
The signal $\text{A0} \sim \text{A8}$ is shown as a bus signal. The area where $\text{A0} \sim \text{A8}$ is hatched is labeled "Row" and "Don't Care".

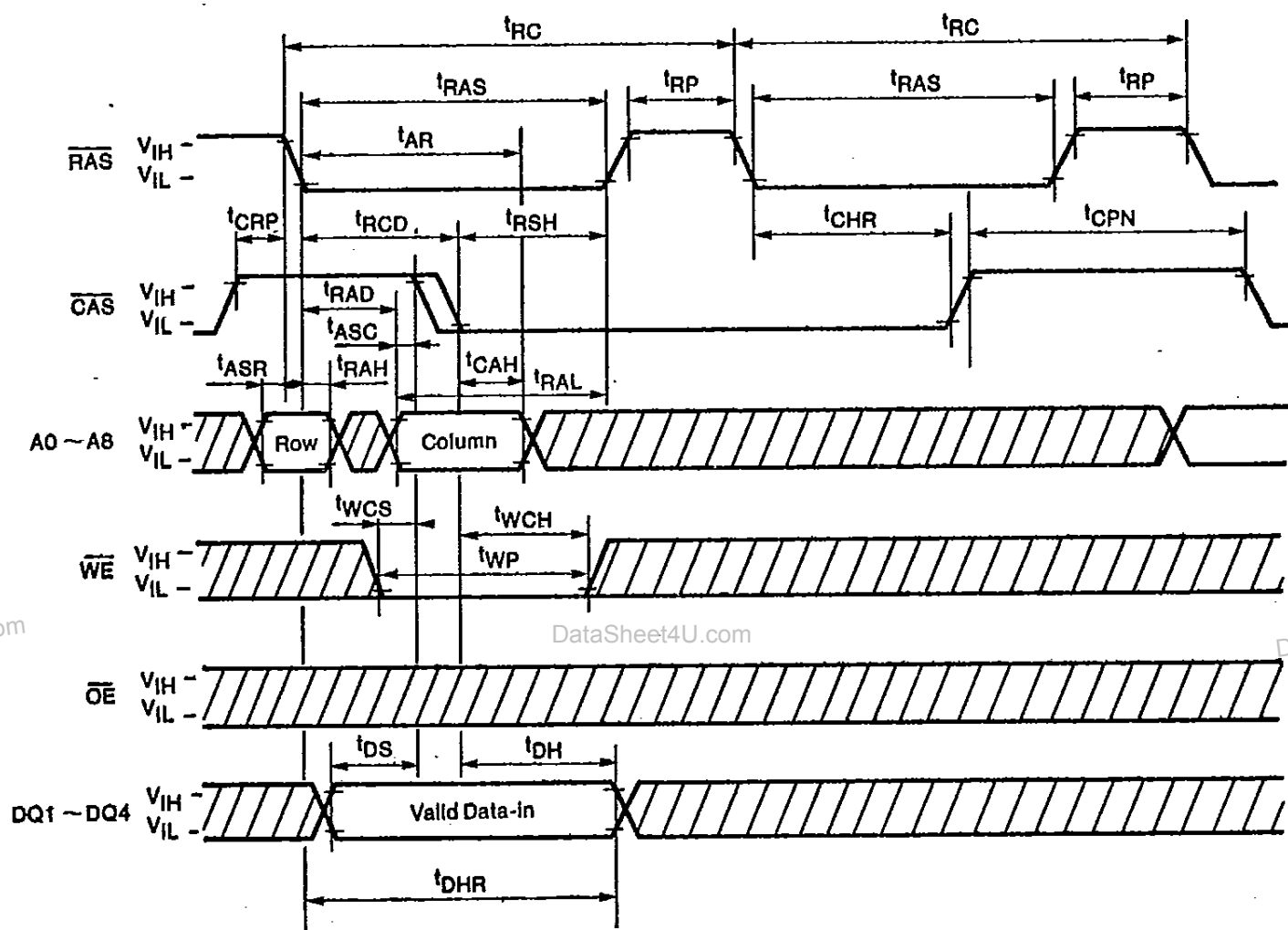
Notes: $\overline{\text{WE}}, \overline{\text{OE}} = \text{Don't Care}$

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HIDDEN REFRESH READ CYCLE





Don't Care

CAS BEFORE RAS REFRESH COUNTER TEST

